Special Issue

Design and Integration of Flexible Electronic Materials/Devices

Message from the Guest Editors

Flexible electronics have been actuated from the continuous development and progress in thin-film materials and devices. These advances have been further boosted by new integration strategies that enable the realizing of bendable, printable, stretchable, and low-cost electronic devices over large areas. Over recent decades, flexible electronics have facilitated much of the technological innovation in the fields of transistors, LEDs, sensors, solar cells, substrates and functional materials, which have found applications on flexible displays, e-paper, RFID, solar cells, senor arrays, biochips, and so on. This Special Issue focuses on the development of design and integration of flexible electronic devices, covers the main topics of (but is not limited to) new material theory and models, device structure and interface design, material preparations and device fabrications, device integrations and circuits, device testing and physical analysis, and large-area manufacturing processes. Work on subjects other than the aforementioned that contribute to advancing knowledge of flexible electronics and their applications are also welcome in this Special Issue.

Guest Editors

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Message from the Editor-in-Chief

Materials (ISSN 1996-1944) was launched in 2008. The journal covers twenty-five comprehensive topics: biomaterials, energy materials, advanced composites, advanced materials characterization, porous materials, manufacturing processes and systems, advanced nanomaterials and nanotechnology, smart materials, thin films and interfaces, catalytic materials, carbon materials, materials chemistry, materials physics, optics and photonics, corrosion, construction and building materials, materials simulation and design, electronic materials, advanced and functional ceramics and glasses, metals and alloys, soft matter, polymeric materials, quantum materials, mechanics of materials, green materials, general. *Materials* provides a unique opportunity to contribute high quality articles and to take advantage of its large readership.

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